Claims

[Claim 1]

A resin composition comprising:

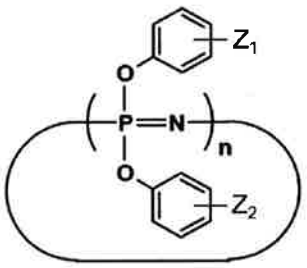
a polyphenylene ether (A) having a number average molecular weight of 500 to 5000, in terms of polystyrene by a GPC method;

a cyclophosphazene compound (B) represented by the following formula (13);

a non-halogen-based epoxy resin (C) having two or more epoxy groups in one molecule;

a cyanate compound (D) having two or more cyanato groups in the molecule; and

a filler (E),

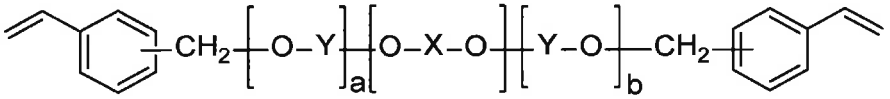


(13)

wherein Z_1 and Z_2 each independently represent a vinyl group or a hydrogen atom, at least either one of Z_1 and Z_2 is a vinyl group, and n represents an integer of 3 to 8.

[Claim 2]

The resin composition according to claim 1, wherein the polyphenylene ether (A) comprises a compound represented by the following formula (4):



(4)